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**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**In re Application of:**

Chopra et al.

**Serial No.:** 10/620,002

**Filed:** July 14, 2003

**For:** SLURRY FOR USE WITH FIXED-  
ABRASIVE POLISHING PADS IN  
POLISHING SEMICONDUCTOR DEVICE  
CONDUCTIVE STRUCTURES THAT  
INCLUDE COPPER AND TUNGSTEN

**Confirmation No.:** 7481

**Examiner:** L. Umez-Eronini

**Group Art Unit:** 1765

**Attorney Docket No.:** 2269-4373.2US  
(00-0036.02/US)

**CERTIFICATE OF MAILING**

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

August 24, 2006  
Date

Signature

Erika Gandre  
Name (Type/Print)

**SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT**

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

In compliance with the duty to disclose information material to patentability pursuant to 37 C.F.R. § 1.56, it is respectfully requested that this Supplemental Information Disclosure Statement be entered and the documents listed on attached Form PTO/SB/08 be considered by the Examiner and made of record. Copies of any cited foreign patents, publications, or pending unpublished U.S. applications are enclosed pursuant to 37 C.F.R. § 1.98(a)(2).

In accordance with 37 C.F.R. § 1.97(g) and (h), filing of this Supplemental Information Disclosure Statement is not to be construed as a representation that a search has been made or an admission that the information cited herein is, or is considered to be, material to patentability as defined in 37 C.F.R. § 1.56(b). Further, no representation is made by Applicants herein that no other possible material information as defined in 37 C.F.R. § 1.56 (b) exists.

Other Documents

GUTMANN, ET AL., Chemical-mechanical polishing of copper with oxide and polymer interlevel dielectrics, Thin Solid Films 270:596-600 (1995).

ZEIDLER, ET AL., The interaction between different barrier metals and the copper surface during the chemical-mechanical polishing, Microelectronic Engineering 37/38:237-249 (1997).

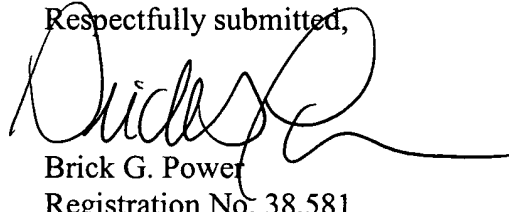
Applicants offer to supply any explanation or discussion of the documents which the Examiner feels is necessary or desirable and which is requested.

This Supplemental Information Disclosure Statement is filed after the mailing date of the first Office Action on the merits.

I hereby certify that no item of information contained in the Supplemental Information Disclosure Statement was first cited in any communication from a foreign patent office in a counterpart foreign application or, to the knowledge of the undersigned after making reasonable inquiry, was known to any individual designated in 37 C.F.R. § 1.56(c) more than three months prior to the filing of the statement, and therefore no fee is due.

**Serial No. 10/620,002**

Respectfully submitted,

A handwritten signature in black ink, appearing to read "Brick G. Power", written over the text "Respectfully submitted,".

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Date: August 24, 2006  
BGP/djp:eg

Enclosures: Form PTO/SB/08  
Cited Non-U.S. Patent Documents

Document in ProLaw



PTO/SB/08B(10-03)

Approved for use through 7/31/2006. OMB 0651-0031

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**INFORMATION DISCLOSURE  
STATEMENT BY APPLICANT**

(use as many sheets as necessary)

Sheet

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of

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**Complete if Known**

Application Number	10/620,002
Filing Date	July 14, 2003
First Named Inventor	Chopra et al.
Group Art Unit	1765
Examiner Name	L. Umez-Eronini
Attorney Docket Number	2269-4373 211S (00-0036 02/11S)

**NON PATENT LITERATURE DOCUMENTS**

Examiner Initials *	Cite No. <sup>1</sup>	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T <sup>2</sup>
		GUTMANN, ET AL., Chemical-mechanical polishing of copper with oxide and polymer interlevel dielectrics, Thin Solid Films 270:596-600 (1995).	
		ZEIDLER, ET AL., The interaction between different barrier metals and the copper surface during the chemical-mechanical polishing, Microelectronic Engineering 37/38:237-249 (1997).	

Examiner  
SignatureDate  
Considered

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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